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PS7241E-1A

4-PIN SOP 400 V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7241E-1A is an optically coupled element that combines a GaAs infrared LED on the input side with a normally-open MOS FET on the output side to realize an excellent cost performance.

The small, thin package and high sensitivity of this element makes it ideal for battery-driven mobile devices, and its small offset voltage at power-on and good linearity are also make it suitable for controlling micro analog signals.

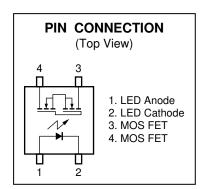
FEATURES

- Small and thin package (4-pin SOP, Height = 2.1 mm)
- 1 channel type (1 a output)
- · Designed for AC/DC switching line changer
- · Low offset voltage
- Ordering number of taping product: PS7241E-1A-E3, E4: 900 pcs/reel
 : PS7241E-1A-F3, F4: 3 500 pcs/reel
 - · Pb-Free product
 - · Safety standards

UL approved: No. E72422BSI approved: No. 8241/8242

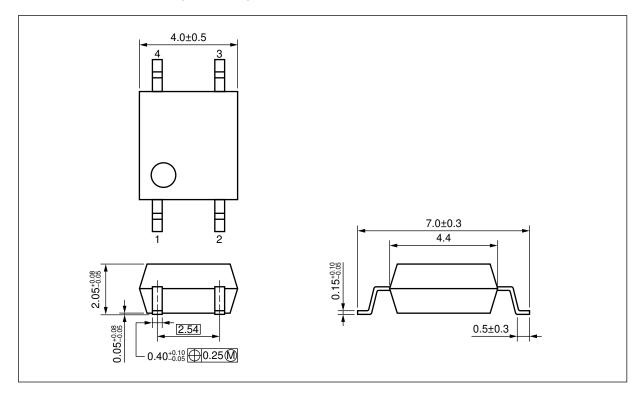
APPLICATIONS

- · Laptop PC, PDA
- Modem card
- · Telephone, FAX
- · Measurement equipment



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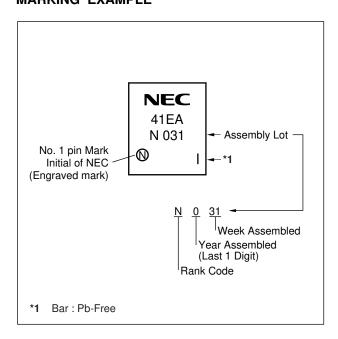
PACKAGE DIMENSIONS (UNIT: mm)



*** PHOTOCOUPLER CONSTRUCTION**

Parameter	Unit (MIN.)		
Air Distance	5 mm		
Outer Creepage Distance	5 mm		
Isolation Distance	0.4 mm		

★ MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7241E-1A	PS7241E-1A-A	Pb-Free	Magazine case 100 pcs	Standard products	PS7241E-1A
PS7241E-1A-E3	PS7241E-1A-E3-A		Embossed Tape 900 pcs/reel	(UL, BSI approved)	
PS7241E-1A-E4	PS7241E-1A-E4-A				
PS7241E-1A-F3	PS7241E-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7241E-1A-F4	PS7241E-1A-F4-A				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	Po	50	mW
	Peak Forward Current *1	IFP	1	Α
MOS FET	Break Down Voltage	VL	400	٧
	Continuous Load Current	lι	120	mA
	Pulse Load Current*2 (AC/DC Connection)	ILP	240	mA
	Power Dissipation	Po	300	mW
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	350	mW
Operating Ambient Temperature		Та	-40 to +85	°C
Storage Temperature		T _{stg}	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output. Pins 1-2 shorted together, 3-4 shorted together.

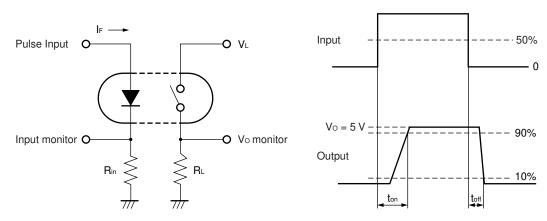
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	4	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	ILoff	V _D = 400 V			1.0	μА
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		50		pF
Coupled	LED On-state Current	IFon	IL = 120 mA			4.0	mA
	On-state Resistance	R _{on1}	IF = 10 mA, IL = 10 mA		22	30	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 120 \text{ mA}, t \le 10 \text{ ms}$		17	23	
	Turn-on Time*1, 2	ton	If = 10 mA, $V_0 = 5$ V, $R_L = 500$ Ω ,		0.5	1.0	ms
	Turn-off Time*1, 2	toff	PW ≥ 10 ms		0.07	0.2	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.5		pF

*1 Test Circuit for Switching Time

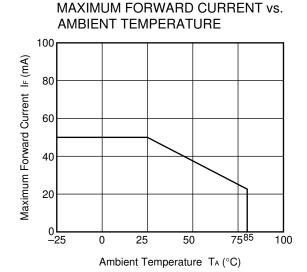


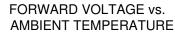
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

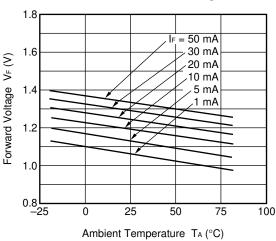
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

100

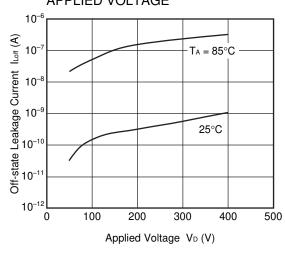
TYPICAL CHARACTERISTICS (Ta = 25°C, unless otherwise specified)



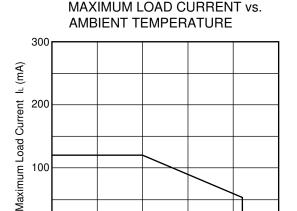




OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



Remark The graphs indicate nominal characteristics.

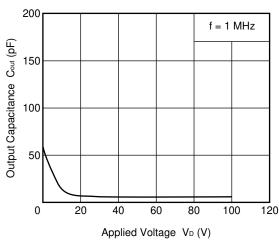


Ambient Temperature T_A (°C)

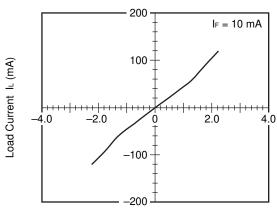
25

0**∟** –25

OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

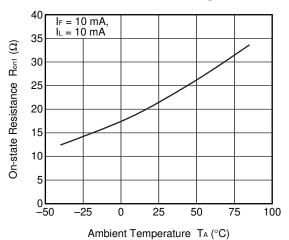


LOAD CURRENT vs. LOAD VOLTAGE

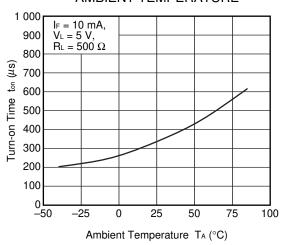


Load Voltage V_L (V)

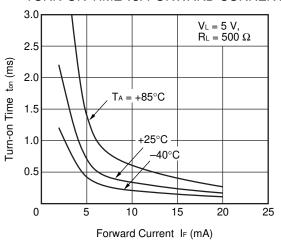
ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



TURN-ON TIME vs. AMBIENT TEMPERATURE

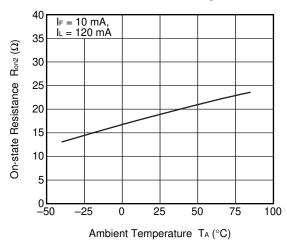


TURN-ON TIME vs. FORWARD CURRENT

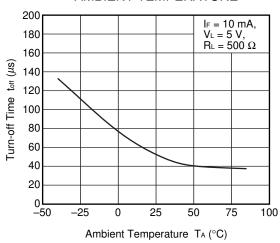


Remark The graphs indicate nominal characteristics.

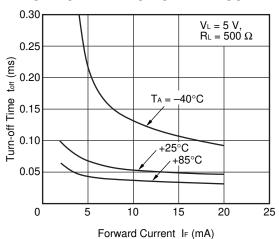
ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



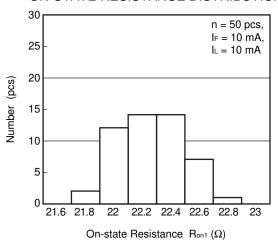
TURN-OFF TIME vs. AMBIENT TEMPERATURE



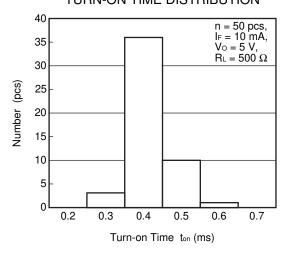
TURN-OFF TIME vs. FORWARD CURRENT



ON-STATE RESISTANCE DISTRIBUTION

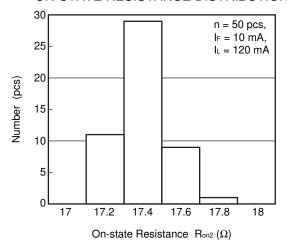


TURN-ON TIME DISTRIBUTION

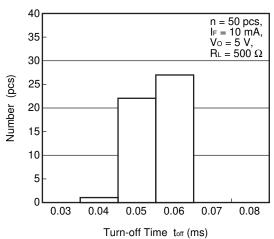


Remark The graphs indicate nominal characteristics.

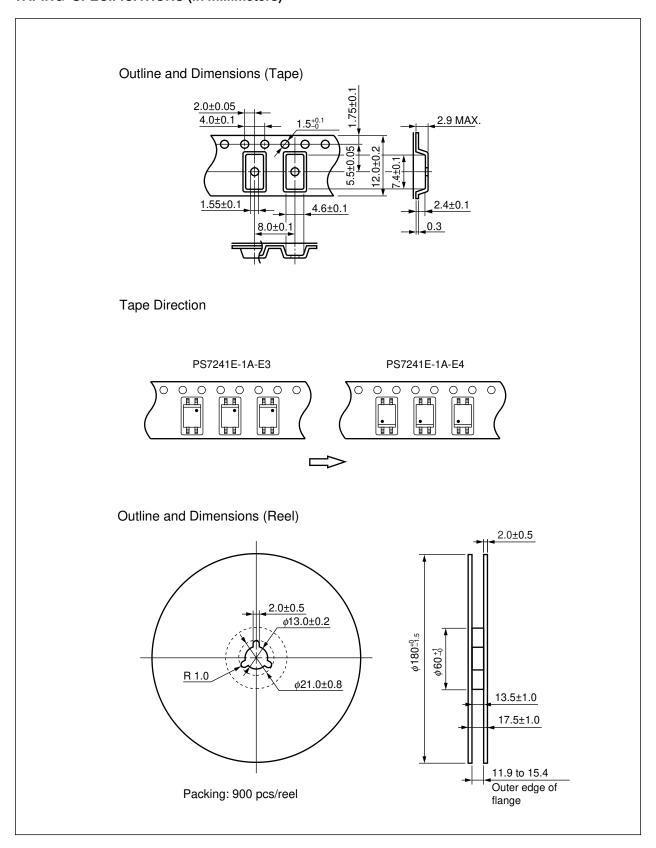
ON-STATE RESISTANCE DISTRIBUTION

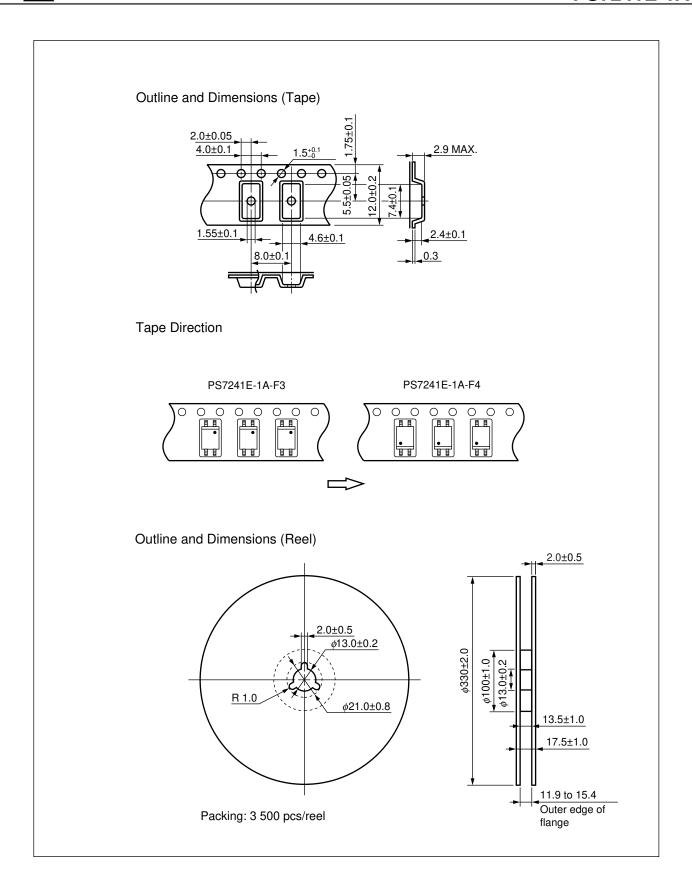


TURN-OFF TIME DISTRIBUTION



TAPING SPECIFICATIONS (in millimeters)





RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

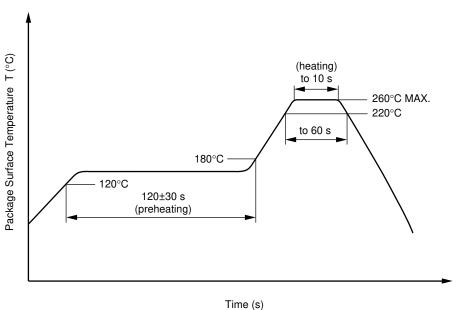
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

Preheating conditions 120°C or below (package surface temperature)

• Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E0904E

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.